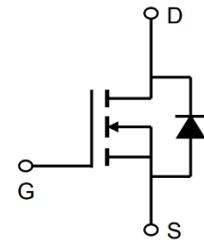


Description

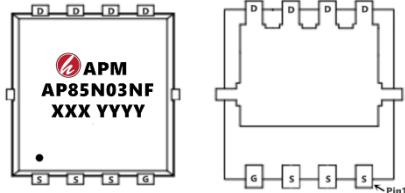
The AP85N03NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



General Features

$V_{DS} = 30V$ $I_D = 85A$

$R_{DS(ON)} < 4m\Omega$ @ $V_{GS}=10V$



Application

Battery protection



Load switch

Uninterruptible power supply

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP85N03NF	PDFN5*6-8L	AP85N03NF XXX YYYY	5000

Absolute Maximum Ratings ($TC=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	85	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	68	A
IDM	Pulsed Drain Current ²	216	A
EAS	Single Pulse Avalanche Energy ³	650	mJ
IAS	Avalanche Current	53.8	A
$P_D@T_c=25^\circ C$	Total Power Dissipation ⁴	45	W
$P_D@T_A=25^\circ C$	Total Power Dissipation ⁴	5	W
TSTG	Storage Temperature Range	-55 to 175	°C
T_J	Operating Junction Temperature Range	-55 to 175	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	25	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	2.8	°C/W

30V N-Channel Enhancement Mode MOSFET
Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	30	33	---	V
$\Delta BVDSS/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.0213	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=30\text{A}$	---	2.3	4	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=15\text{A}$	---	4.3	6	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	-5.73	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=30\text{A}$	20.08	26.5	---	S
Rg	Gate Resistance	$V_{DS}=0\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	1.4	---	Ω
Qg	Total Gate Charge (4.5V)	$V_{DS}=15\text{V}$, $V_{GS}=4.5\text{V}$, $I_D=15\text{A}$	---	70	---	nC
Qgs	Gate-Source Charge		---	12	---	
Qgd	Gate-Drain Charge		---	17	---	
Td(on)	Turn-On Delay Time	$V_{DD}=15\text{V}$, $V_{GS}=10\text{V}$, $R_G=3.3\Omega$ $I_D=15\text{A}$	---	11	---	ns
Tr	Rise Time		---	120	---	
Td(off)	Turn-Off Delay Time		---	25	---	
Tf	Fall Time		---	60	---	
Ciss	Input Capacitance	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	3500	---	pF
Coss	Output Capacitance		---	386	---	
Crss	Reverse Transfer Capacitance		---	358	---	
Is	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	90	A
ISM	Pulsed Source Current ^{2,5}		---	---	360	A
VSD	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_S=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=53.8\text{A}$
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 85A.

Typical Characteristics

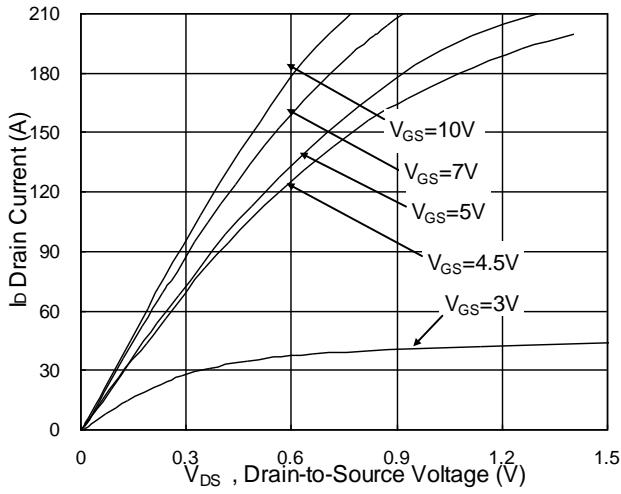


Fig.1 Typical Output Characteristics

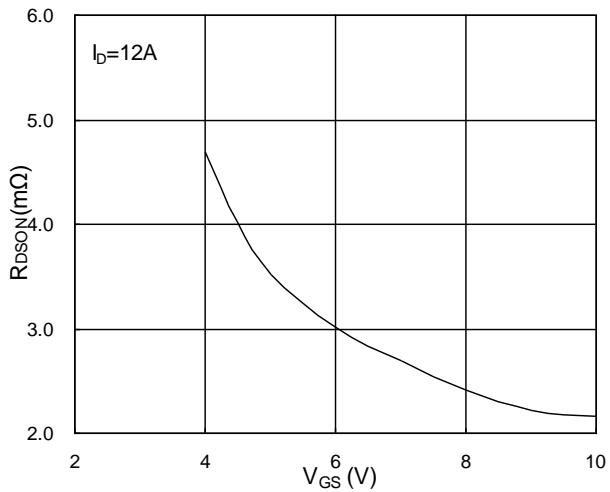


Fig.2 On-Resistance vs. G-S Voltage

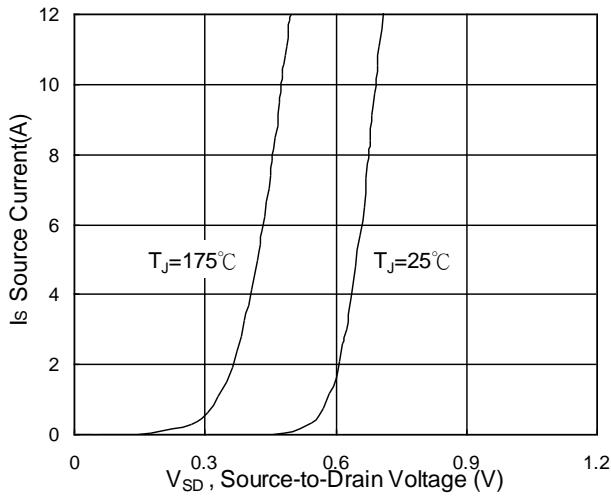


Fig.3 Forward Characteristics of Reverse

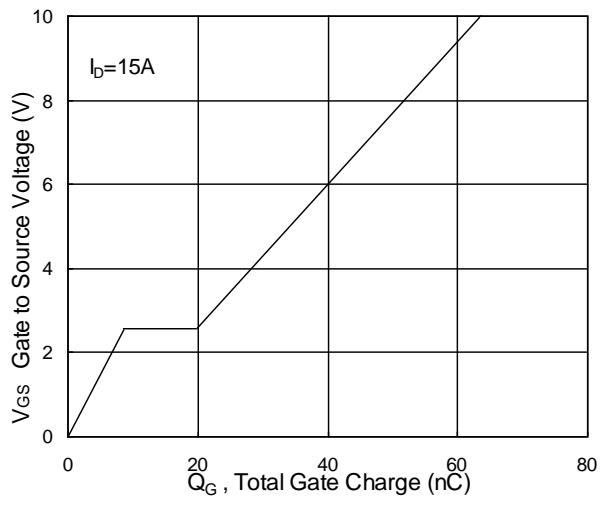


Fig.4 Gate-Charge Characteristics

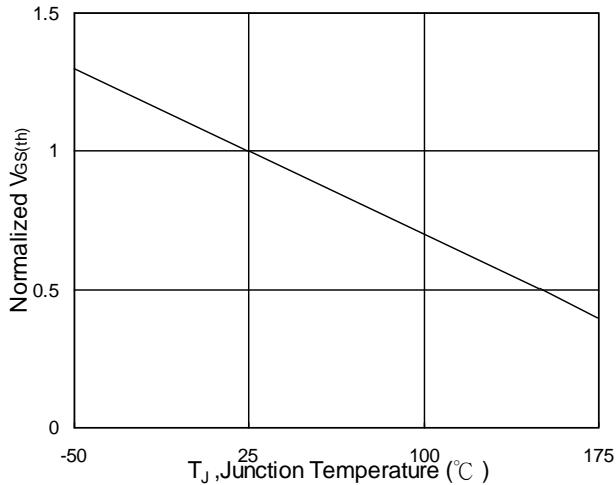


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

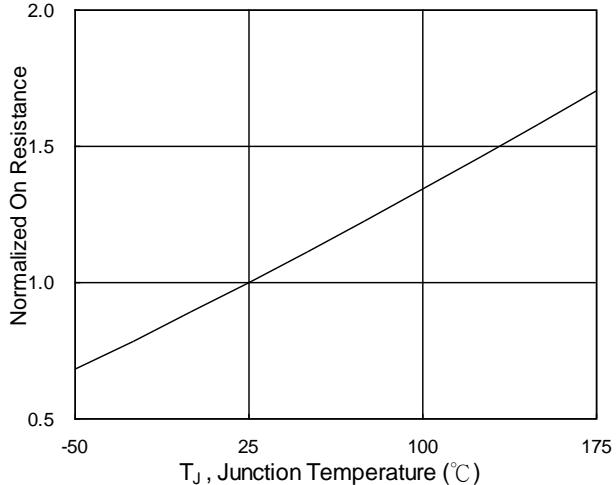


Fig.6 Normalized $R_{DS(on)}$ vs. T_J





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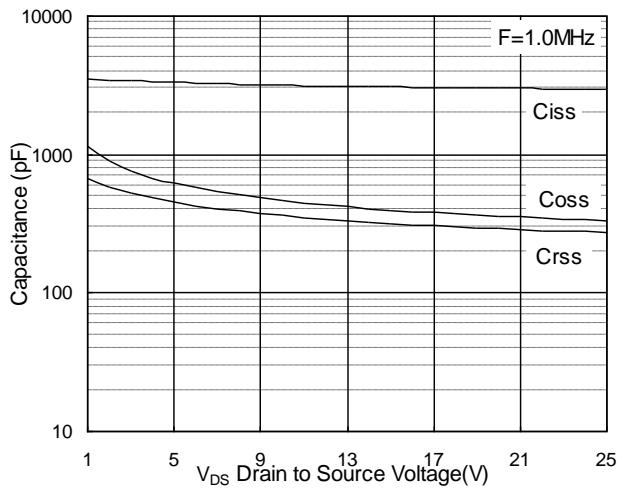


Fig.7 Capacitance

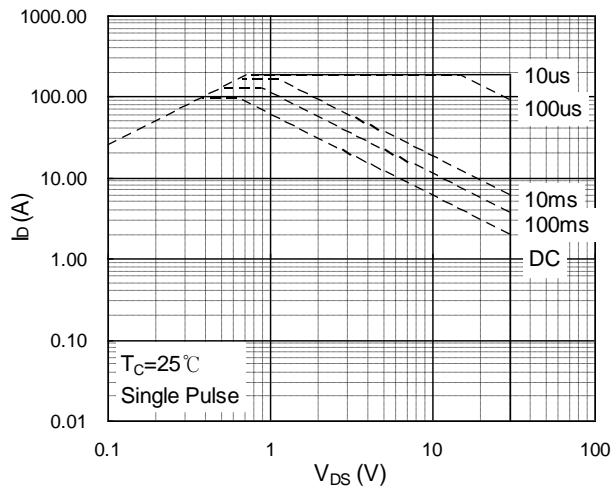


Fig.8 Safe Operating Area

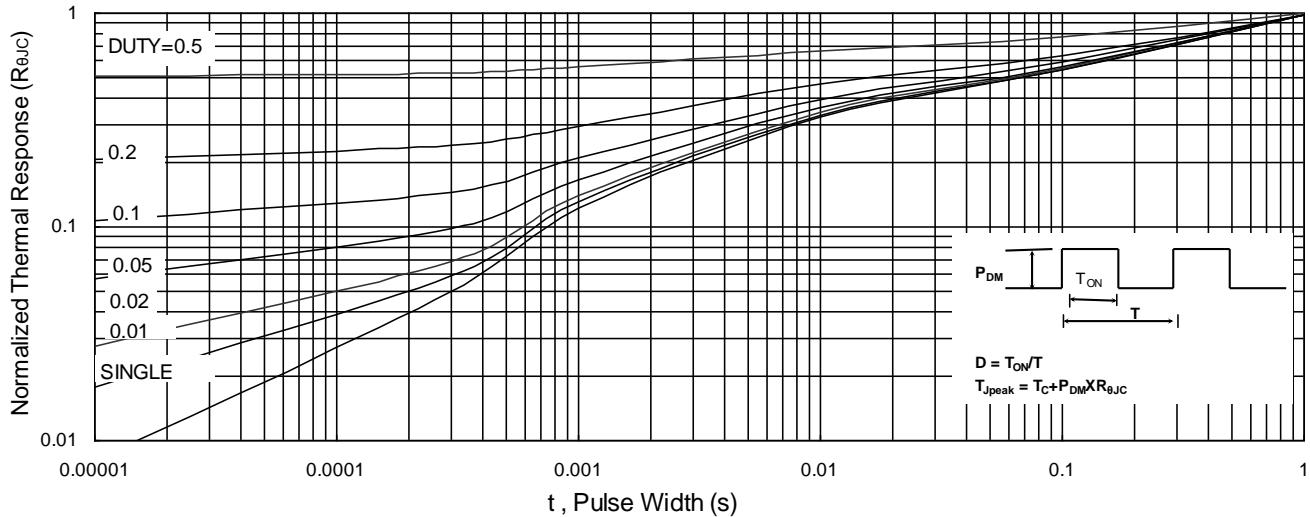


Fig.9 Normalized Maximum Transient Thermal Impedance

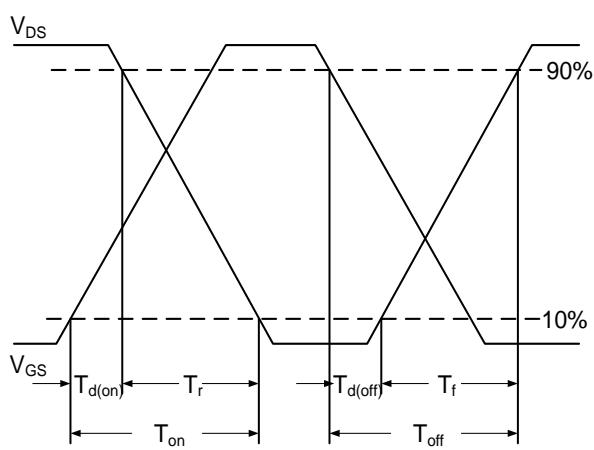


Fig.10 Switching Time Waveform

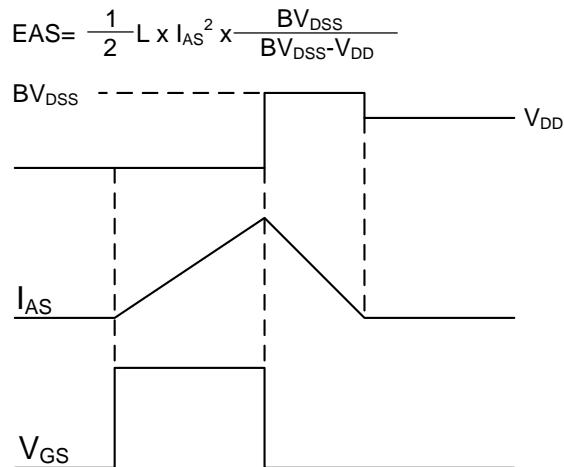
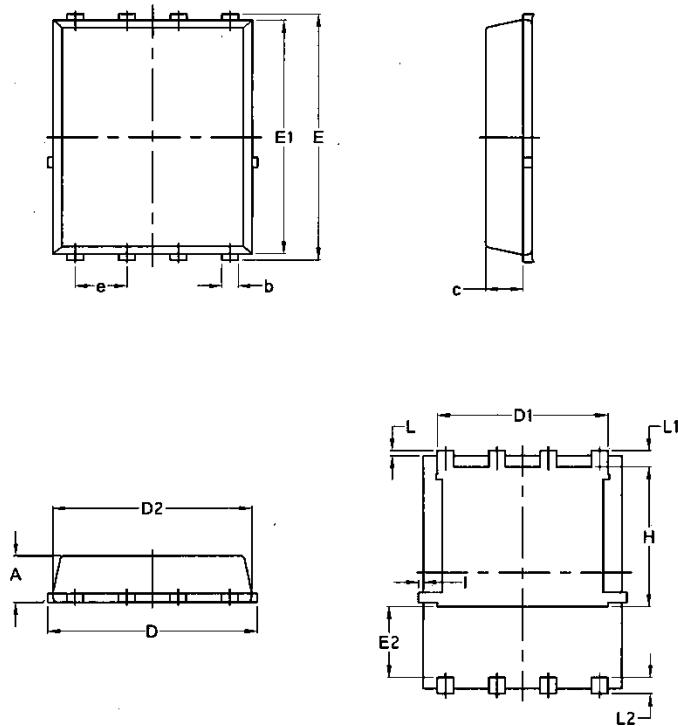


Fig.11 Unclamped Inductive Switching Waveform

Package Mechanical Data-DFN5*6-8L-JQ Single


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070

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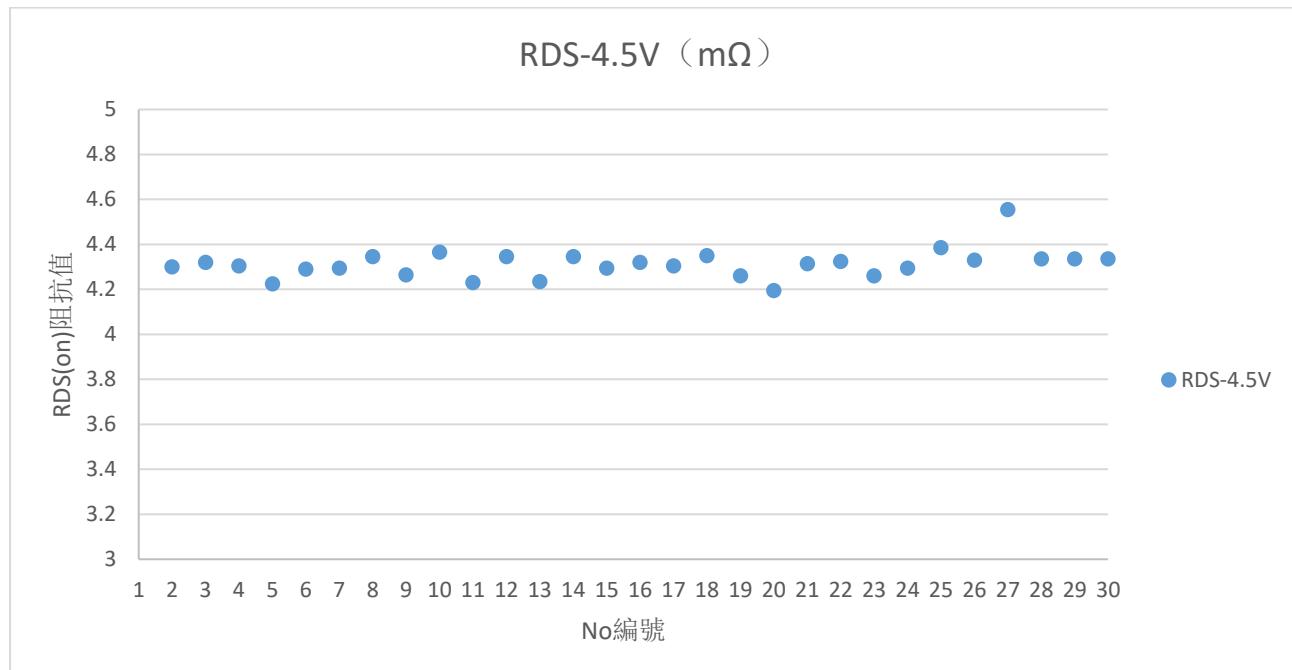
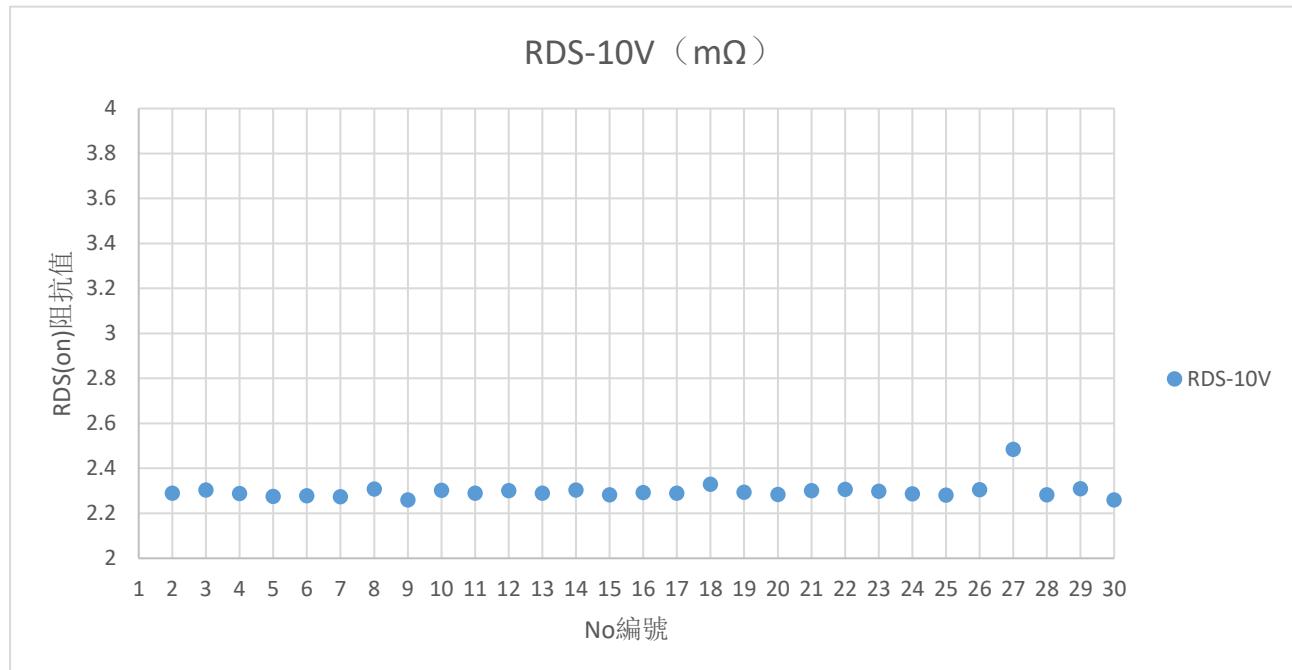
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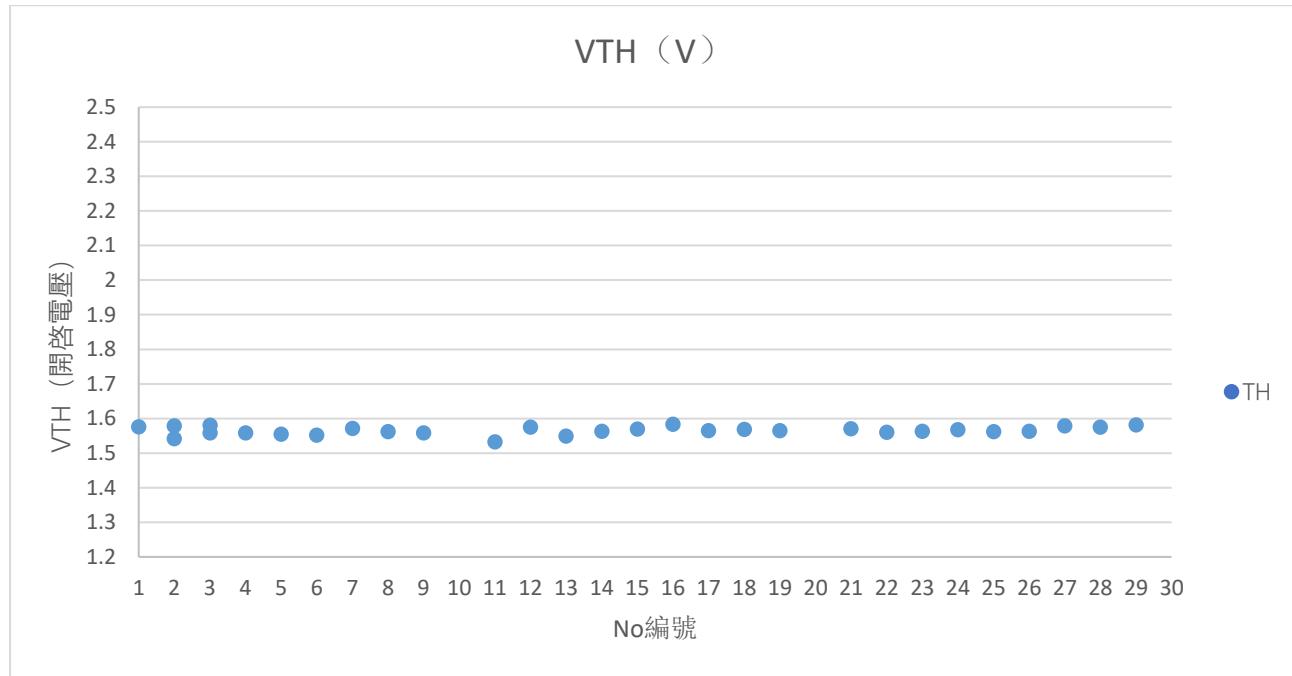
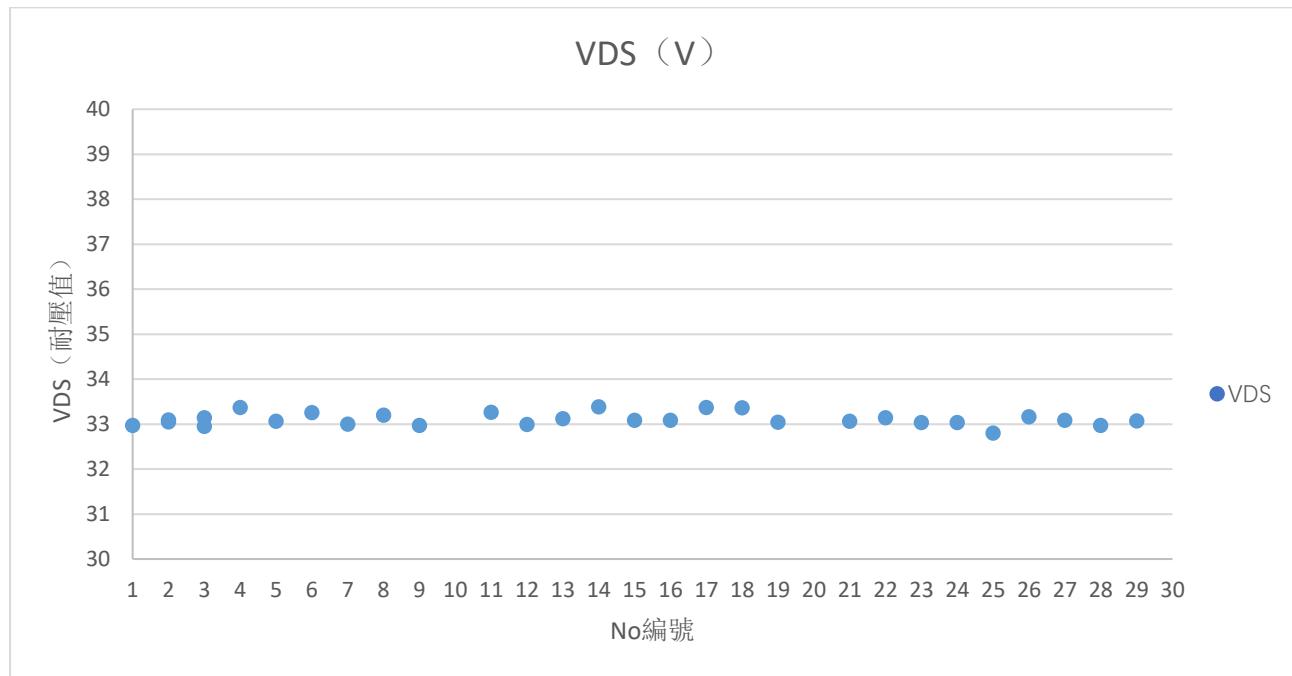
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